

ISAAT2010

19-22 September 2010

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CONFERENCE VENUE

Howard International House, Taipei, Taiwan

REGISTRATION

Delegate: \$500 USD

Student: \$300 USD

Late registration: \$700 USD on/ after July 1, 2010

A delegate registration covers the costs of conference proceedings, welcoming reception, banquet, morning and afternoon refreshments, attendance to all technical sessions, lunches and technical tour. A student registration is not entitled to attend banquet.

IMPORTANT DATES IN 2010

Mar. 31..... Deadline for full paper submission

Apr. 30..... Notification to authors of paper acceptance

May 31..... Final submission of revised papers

Jun. 15..... Conference registration payment deadline

Sep. 19..... Conference registration and reception

Sep. 20-21..... Technical sessions

Sep. 22..... Technical sessions and technical tour

PAPER SUBMISSION

- Papers must be written in English, and is limited to **6** proceedings pages.
- Each paper must be formatted according to the **Instructions for Authors** available in the ISAAT2010 webpage, and submitted via the website: <http://isaat2010.ntu.edu.tw>

PAPER PRESENTATION & PUBLICATION

All papers will be peer reviewed. Accepted papers **MUST** be presented. Each delegate may present up to two papers orally. The conference proceedings will be published as special volumes in an EI indexed international journal: **Advanced Materials Research**. Selected papers will be published in special issues of other international journals currently under discussion.

SYMPOSIUM SECRETARIAT

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Call for Papers

ISAAT2010

The 13th International Symposium on
Advances in Abrasive Technology

19-22 September 2010
Taipei, Taiwan



Organized by

National Taiwan University (NTU)



Sponsored by

National Science Council (NSC)

Ministry of Education (MOE)

The Taiwan Society for Abrasive Technology (TSAT)

International Committee for Abrasive Technology (ICAT)

The Japan Society for Abrasive Technology (JSAT)



<http://isaat2010.ntu.edu.tw>

HISTORY & SCOPE

The International Symposium on Advances in Abrasive Technology (ISAAT) was first held in Sydney, Australia in 1997. Since 2002, JSAT and ICAT have been jointly organizing this exciting annual event for this community and the symposia have been successfully held in US, China, Russia, UK, Turkey, Korea and Japan. An emphasis of the ISAAT series is to bring together both academic researchers and industrial practitioners from around the world for interchange of the latest developments and applications in abrasive technologies. The ISAAT 2010 at the Howard International House, Taipei, Taiwan, will continue to promote the research collaboration and to establish a platform to explore the frontier of abrasive technology.

AREAS OF INTEREST

Contributions of the following areas are invited, but papers in other related areas will also be considered:

- Abrasive machining
- Abrasive jet machining
- Grinding wheel and abrasive grain technologies
- Advanced cutting technology
- CMP and silicon wafer processing
- Truing, dressing, and ELID
- Finishing, lapping, and polishing
- Design, fabrication and analysis of devices for the applications of abrasive technologies
- Glass molding and related topics
- Brittle material machining
- Eco-machining
- EDM, ultrasonic machining, and laser machining
- High speed and high-efficiency machining
- In-process measurement and monitoring, metrology
- Machine tools and systems, tooling processing
- Micro/nano-machining
- Coolants and cooling
- Beam-aided processes
- Surface integrity and materials characterization
- Tribology in manufacturing

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